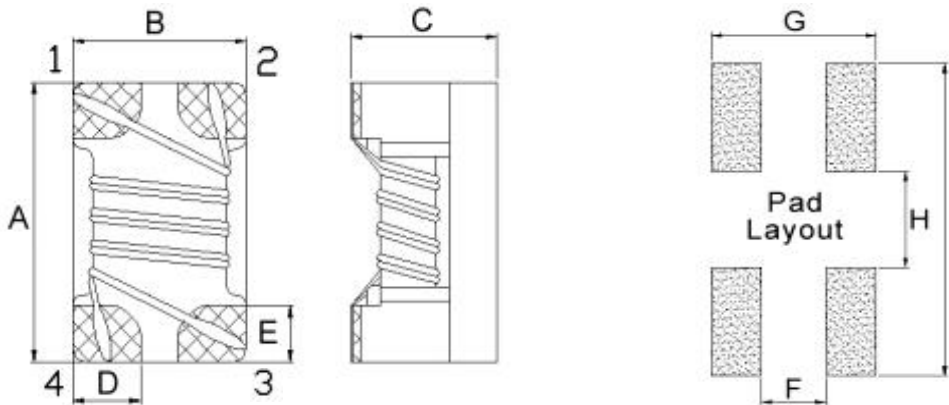


PACKING DIMENSIONS (mm)



3225	Dimensions
A	3.2 ± 0.2
B	2.5 ± 0.2
C	2.2 ± 0.2
D	0.90 Typ
E	0.80 Typ
F	0.60 Typ
G	1.60 Typ
H	1.60 Typ
I	4.40 Typ

EXPLANATION OF PART NUMBERS

1	2	3	4	5	6	7	8	9	10	11	12
S	W	M	3	2	2	5	S	9	0	0	H
(1)			(2)			(3)					

(1) Product name

(2) Shapes and dimensions

(3) Impedance 【 at 100MHz 】

900:90

ELECTRICAL CHARACTERISTICS

P/N	Z(Ω)	DCR (Ω)	Rated current	Rated Voltage	Insulation Resistance
	Common Mode				
	Impedance at 100MHz				
		[Max]	Idc(A)	Vdc	IR
			[Max]	(V)Typical	(MΩ)Min.
SMW3225S900HTE	90±25%	0.10	1	50	10

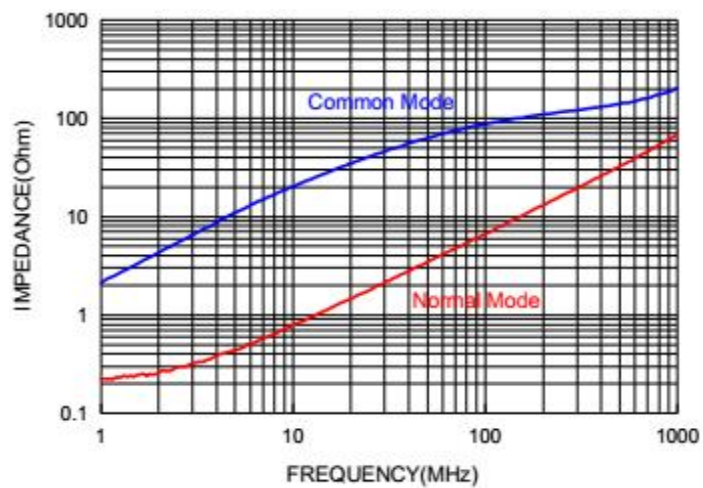
Operating temperature : -25 to +85°C

Storage temp. and humidity : -40 to +85°C ,70%RH max

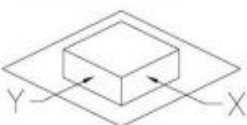
Typical Heat Rating DC Current would cause an approximately ΔT of 40°C

PERFORMANCE CURVES

SMW3225S900HTE

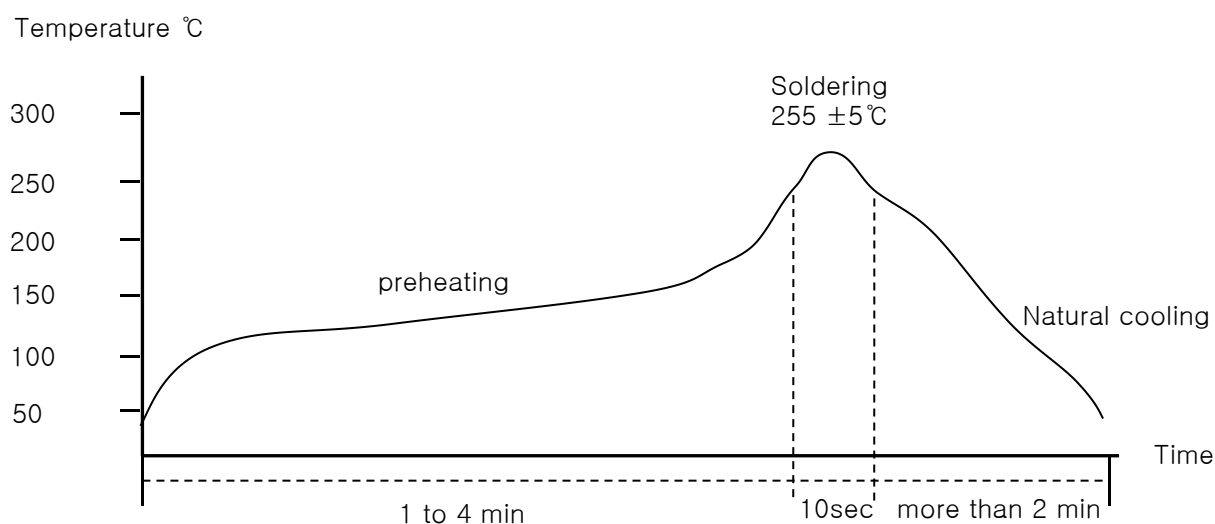


◆ RELIABILITY TESTING

Operating Temperature	- 40 to +125 °C (Contain Heating coil)
Appearance Inspection	No external defects by visual inspection
Terminal Strength 	After soldering , between copper plaet and terminals of coils , push in two directions of X , Y with standing 10N(1.02kg) for10+/-2 sec. Terminal should not peel off. (Refer to figure at right)
Heat endurance of reflow soldering	Refer to figure
Insulating resistance	Over 10 MΩ at 50V D.C . between wire and core
Dielectric Strength	Apply at 0.5KV 1mA for 3S between wire and core
Temperature characteristics	Inductance coefficient (0~2,000) × 10 / °C (- 40~ + 125 °C)
Humidity characteristics	Inductance deviation within ± 10% , after 96 hours in 90~95% relative humidity at 40 ± 2 °C and 1 hours drying under normal condition

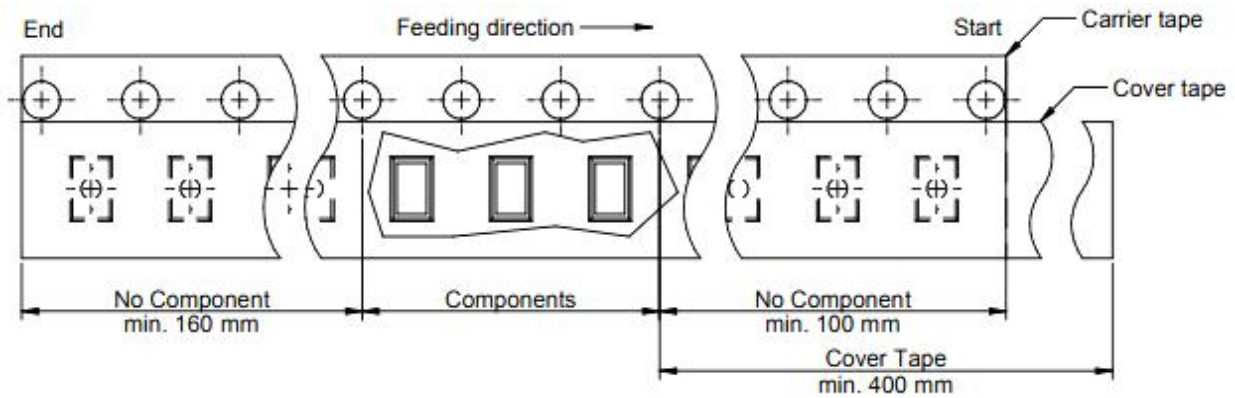
A test is made under the above mentioned condition , and it is kept for 2 hours in the normal

IR Reflow profile

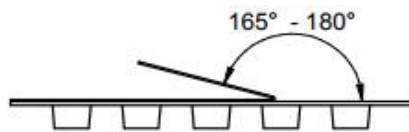


Temperature and humidity . After that , no mechanical and electrical defect should be found .

◆ PACKING SPECIFICATIONS



Transparent carrier and cover tape



Tape width	Distance	Pull-of force
8 mm	4 mm	10~120g